

SEMICONDUCTOR

Precision cleaning of processing equipment and tooling with dry ice

In semiconductor production, the processing equipment must be kept extremely clean in order to prevent product contamination. Traditional cleaning methods present challenges, including costly downtime, the use of chemicals and solvents, hazardous waste disposal and employee exposure to harmful chemicals. Dry ice precision cleaning is an effective method used to decontaminate semiconductor manufacturing equipment. The environmentally responsible cleaning and surface preparation process is aggressive enough to quickly remove deposition and contamination without impacting the substrate material. Dry ice is non-abrasive on metal, ceramics and many other substrates and is able to quickly remove all surface contaminants from even the most difficult areas of the processing equipment without creating a secondary waste stream.

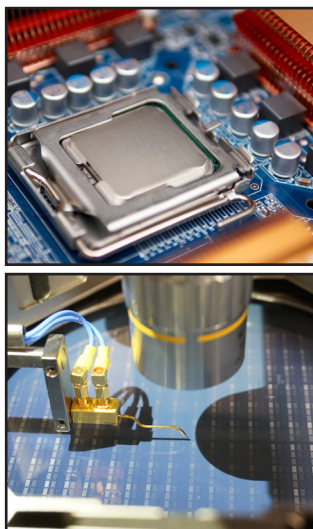
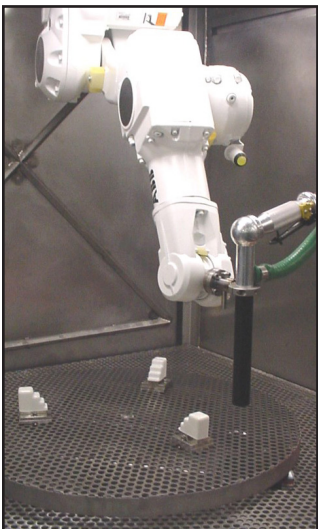
KEY BENEFITS

- **Faster, more effective clean**
- **Clean in-place without lengthy disassembly**
- **Non-abrasive, non-flammable & non-conductive**
- **Reduction or elimination of solvents/acids**
- **Lower operating costs**
- **Elimination of grit entrapment**
- **Safer for employees**
- **No secondary waste stream**
- **Environmentally responsible**

Wafers
Masks/Shields
Chemical Mechanical Polishing (CMP)
Vacuum pumps
Conformal coating removal off PCB
Wafer chamber tooling and components

Implanters
Ceramic support discs
Polycrystalline silicone reactors
Deposition tooling
Polishing tooling

APPLICATIONS



Join industry leaders already benefiting from Cold Jet dry ice cleaning systems.



PHILIPS

